



**MODEL:** HSB07-202009 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- top mount
- aluminum alloy
- black anodized finish



**MODEL**

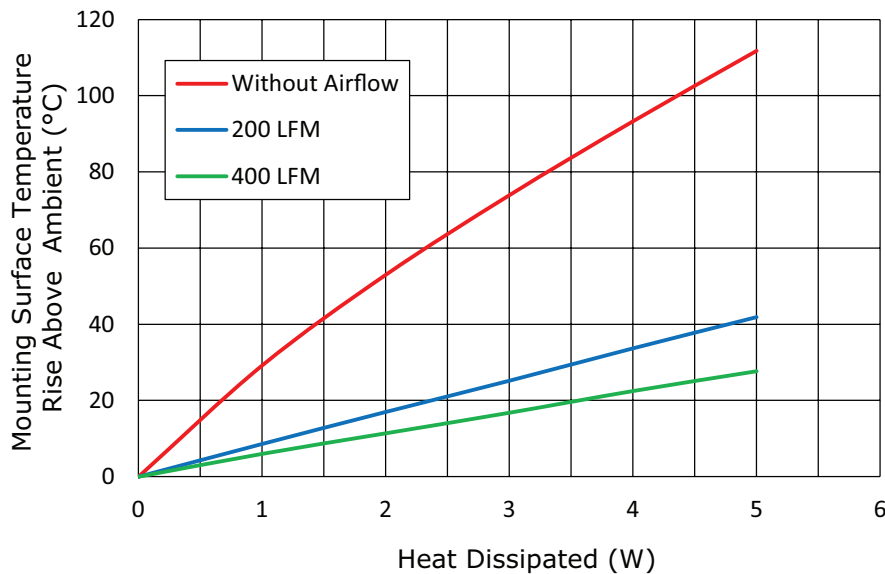
HSB07-202009	thermal resistance <sup>1</sup>			power dissipation <sup>1</sup> @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	24.08	29.2	8.6	3.11

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	29.2	8.6	6.0
2	53.0	17.0	11.4
3	73.9	25.2	16.8
4	93.3	33.7	22.5
5	111.8	41.9	27.7

T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
T<sub>a</sub>: ambient temperature



## MECHANICAL DRAWING

units: mm  
tolerance:  $\pm 0.38$  mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	3.7 g

